



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): SHIMOKAWA, et al.

Serial No.: 09/972,178

Filed: October 9, 2001

For: PB-FREE SOLDER-CONNECTED STRUCTURE AND
ELECTRONIC DEVICE

Group: 1775

Examiner: J. Zimmerman

AMENDMENT

June 30, 2003

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action mailed December 31, 2002, please amend
the above-identified application as follows:

IN THE CLAIMS

✓
Please cancel claims 1-5, 24-27, 40-42, 50-61, 68, 69 and 72-77 without
prejudice or disclaimer, and amend the claims remaining in the application as
follows:

DI
6. (Twice Amended) An electronic device comprising a substrate and a
semiconductor device, which are connected with each other by means of a Pb-free
solder, the semiconductor device having a lead on which an Sn-Bi alloy plating layer

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500.38665CX1

GROUP 1700

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